

United States Patent and Trademark Office

Application No.:	10/812,562	Confirmation No.:	3668
Filed:	March 30, 2004	TC/A.U.:	3723
Customer No.:	51111	Examiner:	Maurina T. Rachuba
Docket No.:	NRCAP024	Applicant:	Yi-Ping Hsin et al.
Title:	WAFER POLISHING CONTROL SYSTEM FOR CHEMICAL MECHANICAL PLANARIZATION MACHINES		

Commissioner for Patents
POB 1450
Alexandria, VA 22313-1450

Amendment B

Dear Sir:

In response to the office action of February 1, 2006, please amend the above-identified application as follows.

Amendments to the claims are reflected in the listing of claims that begins on page 2 of this paper.

Remarks begin on page 6 of this paper.